

Session 2: Microassembly

Micro Manipulation System for Mechanical Assembly

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Development of Microassembly Systems with Haptic Interface

S. Kahn. *Delft University of Technology, The Netherlands*; A. Sabanovic, V. Patoglu. *Sabanci University, Turkey*.

A Versatile and Reconfigurable Microassembly Workstation

E. Kunt, A. Naskali, K. Cakir, A. Sabanovic. *Sabanci University, Turkey*; E. Yuksel. *Gebze Institute of Technology, Turkey*.

A Flexible, Modular Micro-Assembly System for a Family of Miniature Spin Bearings

N. Fezie, R. DeVor, S. Kapoor. *University of Illinois at Urbana Champaign, U.S.A.*

Size-adapted Devices and Processes for High Precision Assembly Tasks

A. Raatz, A. Burisch, K. Schottler, J. Wrege. *Technische Universitat Braunschweig, Germany*.

Micromanufacturing process integration

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